

## Thermal RC network (Foster)

## SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
₹ <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base		-	-	2.00	K/W
	Cth <sub>1</sub>	1.858E-05 F		Ą	4.	
	Cth <sub>2</sub>	8.466E-05 F		<b>_</b>	<u> </u>	
	Cth <sub>3</sub>	2.486E-04 F				
	Cth <sub>4</sub>	1.014E-03 F				
	Cth <sub>5</sub>	2.305E-03 F			$\int Rth_1 + Cth_2$	1
	Cth <sub>6</sub>	1.614E-02 F			<b></b>	
	Cth <sub>7</sub>	6.607E-02 F		г	<b>۲</b> • − 1	
	Cth <sub>8</sub>	1.199E+01 F			$\int Rth_2 + Cth_2$	2
	Rth₁	5.097E-03 Ω				
	Rth <sub>2</sub>	1.228E-02 Ω		_   _ г		
	Rth <sub>3</sub>	3.904E-02 Ω				3
	Rth <sub>4</sub>	1.089E-01 Ω			┎	
	Rth₅	3.852E-01 Ω			<u></u>	
	Rth <sub>6</sub>	7.032E-01 Ω			Rth4 📥 Cth	4
	Rth <sub>7</sub>	7.333E-01 Ω			<b></b>	+
	Rth <sub>8</sub>	1.295Ε-02 Ω	(	Р		
				Ţ		5
						8
				l	┘╺╶┬╴╴┈	0
				[		
				l	Rth7 📥 Cth	7
Part:	PSMN5R0-30YL			ſ		
Date:	18/11/2015				$\int Rth_8 \stackrel{\bullet}{=} Cth_8$	В
Nodel Rth	2.00 K/W					
					t <sub>amb</sub>	
				$\vee$	001aal76	8

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